12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260514000.1
Qualification of RFAB as additional Fab Site, Die Revision, BOM Changes, TI ChengDu as additional Assembly Site and Datasheet update for select devices
Change Notification / Sample Request

Date: May 18, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260514000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74AVC2T245RSWR	SN74AVC2T245RSWR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260514000.1	**PCN Date:**	May 18, 2026
Title:	Qualification of RFAB as additional Fab Site, Die Revision, BOM Changes, TI Chengdu as additional Assembly Site and Datasheet update for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 16, 2026	**Sample requests accepted until:**	July 17, 2026

***Sample requests received after** July 17, 2026 **will not be supported.**

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
FFAB	A3C10TPI	200mm	RFAB	LBC7	300mm

Texas Instruments is pleased to announce the qualification of TI Chengdu (CDAT) as an additional Assembly site, for the list of devices shown below. Material differences between sites are as follows.

	Current Sites				Additional BOM Changes	Additional Site
Assembly Site	JCETJY	ATXSZ	HNA	UTL1 & UTL3	ATXSZ	CDAT
Lead Finish	NiPdAu	NiPdAu	NiPdAuAg	NiPdAu	NiPdAu	NiPdAu
Bond Wire	Au 0.8mil	Au 0.8mil	Au 0.8mil	Au 0.6mil	PCC 0.7mil	PCC 0.8mil
Mold Compound	S#12090 3003709	SID#1801 512111	SID#4501 76	SID#CZ01 36	SID#1801 651111	4222198
Mount Compound	S#12040 2001600	SID#1400 238112	SID400194	SID#PZ00 37	SID#1400 336111	4226215

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised

datasheets are available in the table below.

Changes from Revision D (February 2016) to Revision E (September 2024) **Page**

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74AVC2T245	SCES692D	**SCES692E**	SN74AVC2T245 data sheet, product information and support | TI.com

Qual details are provided in the Qual Data Section.

Reason for Change:

New wafer fab (RFAB) which results in the process change to LBC7 and assembly BOM change.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the updated Standard Data Packet for more details on the changes.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If the boxes below are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Wafer Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
-	**A**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ATXSZ	ASN	CHN	Suzhou
HNA	HNA	TH	Ayutthaya
JCETJY	JCE	CHN	Jiangyin
UTL1	UT1	TH	Bangkok
UTL3	UT3	TH	Bangpakong
CDAT	**CDA**	**CHN**	**Chengdu**

Sample product shipping label (not actual product label)

Product Affected:

SN74AVC2T245RSWR

Qualification Data

Qualification Report

FAB5 AVC2T RSW-CDAT (Commercial)
Approve Date 21-October -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC2T245RSWR	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: INA190A1IRSWR-S	QBS Package Reference: INA190A3IRSWR-S	QBS Package Reference: INA190A5IRSWR-S	QBS Product Reference: CAVC2T45TDCURQ1	QBS Product Reference: SN74AVC2T245RSWR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	1/77/0	1/77/0	1/77/0	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	1/77/0	1/77/0	1/77/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	1/77/0	1/77/0	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	1/77/0	1/77/0	1/77/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	-	-	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	1/5/0	1/5/0	1/5/0	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	1/5/0	1/5/0	1/5/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	1/3/0	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC2T245RSWR	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: INA190A1IRSWR-S	QBS Package Reference: INA190A3IRSWR-S	QBS Package Reference: INA190A5IRSWR-S	QBS Product Reference: CAVC2T45TDCURQ1	QBS Product Reference: SN74AVC2T245RSWR
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	3/90/0	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74AVC2T245RSWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-078

Qualification Report

FAB5 AVC2T RSW-ASEN (Commercial)
Approve Date 21-October -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC2T245RSWR	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: CAXC2T245QRSWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	3/230/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	-
HTSL	A6	High Temperature Storage Life	175C	1000 Hours	-	-	1/45/0
HTOL	B1	Life Test	150C	300 Hours	-	3/231/0	3/231/0
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AVC2T245RSWR	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: CAXC2T245QRSWRQ1
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SN74AVC2T245RSWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2308-079

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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